



Material Content Data Sheet



Sales Product Name		BSP613P H6327		Issued		19. July 2018		
MA#		MA001071052						
Package		PG-SOT223-4-21		Weight*		113.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.043	0.04		377	
	noble metal	gold	7440-57-5	0.167	0.15		1464	
	inorganic material	silicon	7440-21-3	1.890	1.66	1.85	16586	18427
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		89	
	non noble metal	titanium	7440-32-6	0.051	0.04		445	
	non noble metal	chromium	7440-47-3	0.152	0.13		1335	
	non noble metal	copper	7440-50-8	50.489	44.31	44.49	443044	444913
wire	non noble metal	copper	7440-50-8	0.096	0.08	0.08	844	844
encapsulation	organic material	carbon black	1333-86-4	0.591	0.52		5185	
	plastics	epoxy resin	-	8.863	7.78		77770	
	inorganic material	silicondioxide	60676-86-0	49.631	43.55	51.85	435512	518467
leadfinish	non noble metal	tin	7440-31-5	1.464	1.28	1.28	12847	12847
plating	noble metal	silver	7440-22-4	0.513	0.45	0.45	4502	4502
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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